



Features and Benefits

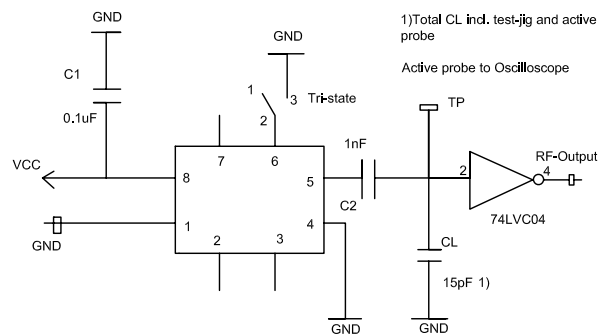
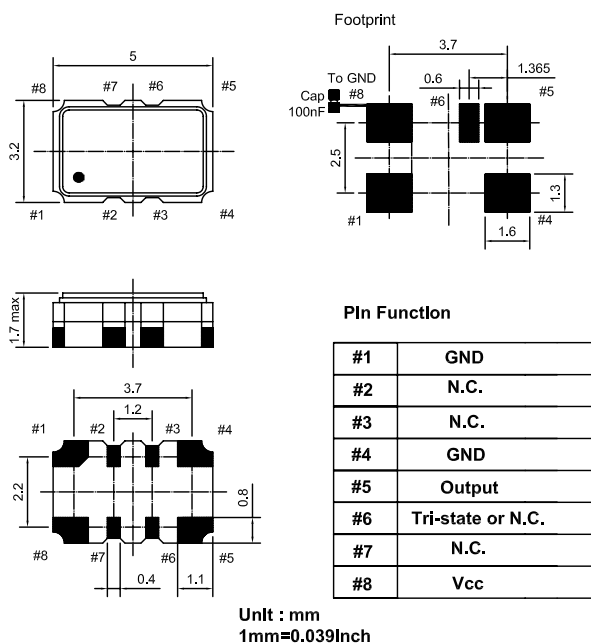
Custom design for SATCOM clock reference frequency of 10.23MHz
 Low case height SMD package: less than 1.7mm max
 Low Phase Noise: less than -140dBc/Hz @ 1KHz
 Less than 5E-11 short term stability for tau = 1 second gate
 Better than ±0.5PPM from -40°C to +85°C
 3.3V supply; 3mA maximum

Typical Applications

Mobile Radio
 Communication Equipment

Mechanical Drawing & Pin Connections

Drawing No:MD150017-5



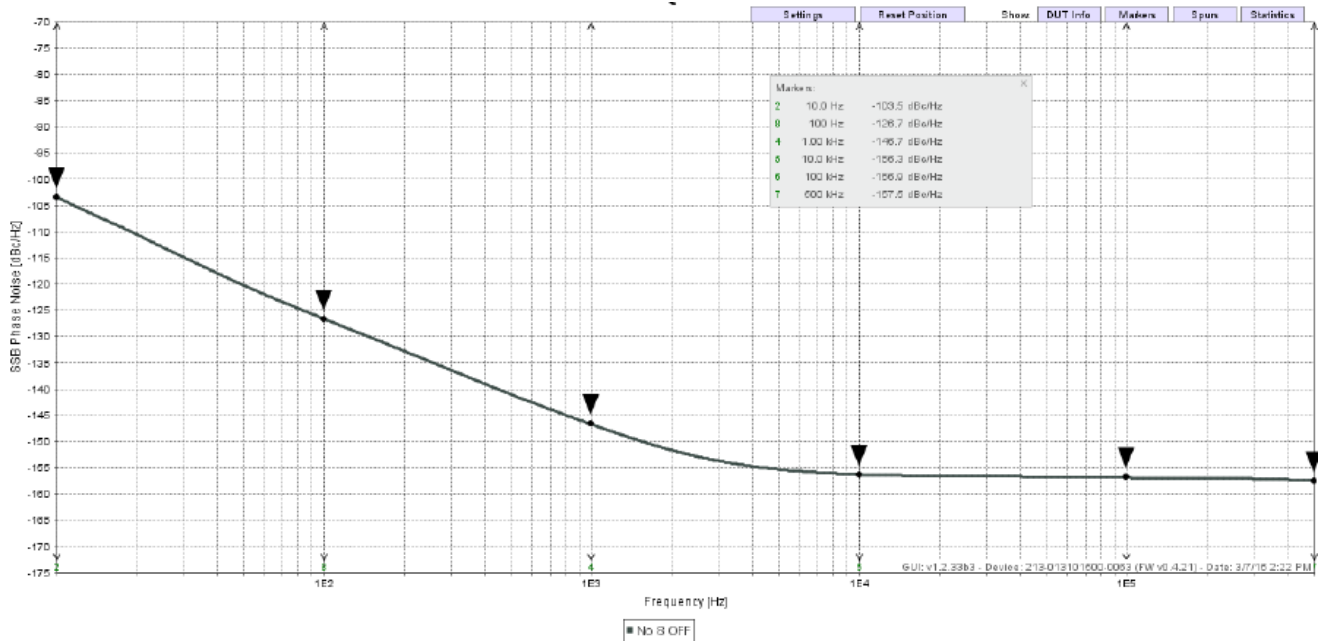


Specifications

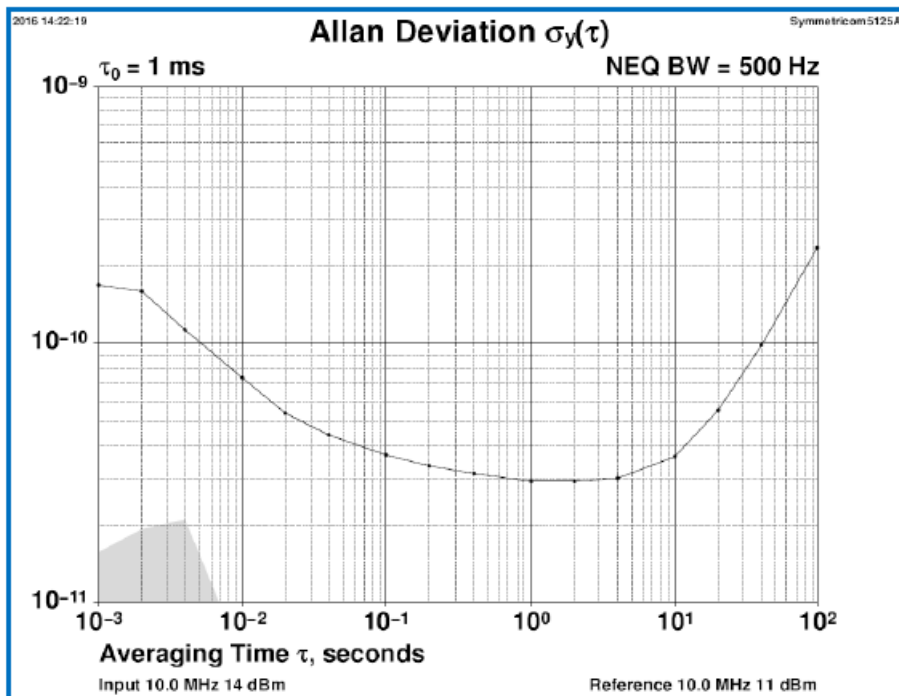
Oscillator Specification	Sym	Condition	Value			Unit	Note
			Min.	Typ.	Max.		
Nominal Frequency	F ₀			10.2300		MHz	
RF Output							
Output Wave Form			CMOS				
Output Level	V _{OH}		2.97			V	
	V _{OL}				0.33	V	
Load				12	15	pF	
Power Supply							
Voltage				+3.3		V	
Current Consumption				<3		mA	
Frequency Stability							
VS. Tolerance ex factory		@ +25°C	0.0		+1.0	ppm	
VS. Temperature Reference (F _{MAX} +F _{MIN})/2		Over -40°C to +85°C		±0.5		ppm	
VS Supply Voltage Change Reference to frequency at nominal supply		±5%		±0.1		ppm	
VS. Load Change Reference to frequency at nominal load		±10%		±0.1		ppm	
Aging		1 st year		±1.0		ppm	
Frequency Slope		Over operating temperature		≤0.05		ppm/°C	
Short Term Stability ADEV		T = 1.0 s		<5 x 10 ⁻¹¹			
Tri-state function		Pin #6 = 2.1V or open Pin #6 = 0.9V or GND				pin#5 → oscillation pin#5 → high impedance	
Phase Noise							
Phase noise 10.23 MHz		@ 1 kHz			-140	dBc/Hz	
		@ 10 kHz			-150		
		@ 100 kHz			-155		
Environmental Conditions							
Parameter	Reference Std.						
Operating Temperature Range	-40°C to +85°C						
Storage Temperature Range	-55°C to +105°C						
Reflow Profiles as per JEDEC J-STD-020C	≤260°C maximum during 10 sec. max						
Moisture Sensitivity	Level 1 (unlimited)						
Packing Units	Tape and Reel 500 or 1000 pcs						



Phase Noise



Allan Deviation





Environmental Conditions

Test	IEC 60068 Part ...	IEC 60679-1 Clause	MIL-STD-202G Method	MIL-STD-810F Method	MIL-PRF-55310D Clause	Test Conditions (IEC)
Sealing Tests (if applicable)	2-17	5.6.2	112E		3.6.1.2	Gross leak: Test Qc. Fine leak: Test Qk
Solderability Resistance to Soldering Heat	2-20 2-58	5.6.3	208H 210F		3.6.52 3.6.48	Test Ta method 1 Test Td ₁ method 2 Test Td ₂ method 2
Shock	2-27	5.6.8	213B	516.4	3.6.40	Test Ea, 3 x per axis, 100 g 6 ms half-sine pulse
Vibration Sinusoidal	2-6	5.6.7.1	201A 204D	516.4-4	3.6.38.1 3.6.38.2	Test Fc, 30 min per axis, 1 oct/min 10 Hz – 55 Hz 0.75 mm; 55 Hz – 2 kHz 10g
Vibration Random	2-64	5.6.7.3	214A	514.5	3.6.38.3 3.6.38.4	Test Fdb
Endurance Tests - Aging - Extended Aging		5.7.1 5.7.2	108A		4.8.35	30 days @ 85°C 1000 h, 2000 h, 8000 h @ 85°C

Handling Precautions

Flux Residue Resistance

Yes, even an unclean board can affect analog circuit performance.

Be aware if the circuit has very high resistances – even in the low MΩ - special attention may need to be paid to cleaning. A finished assembly may be adversely affected by flux or cleansing residue. The electronics industry in the past few years has joined the rest of the world in becoming environmentally responsible. Hazardous chemicals are being removed from the manufacturing process – including flux that has to be cleaned with organic solvents. Water-soluble fluxes are becoming more common, but water itself can become contaminated easily with impurities. These impurities will lower the insulation characteristics of the PCB substrate. It is vitally important to clean with freshly distilled water every time a high-impedance circuit is cleaned. There are applications that may call for the older organic fluxes and solvents, such as very low power battery powered equipment with resistors in the 10s of MΩ range. Nothing can beat a good vapor defluxing machine for ensuring that the board is clean